

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5	"10/673501" "10/673583" "10/673138"	US-PGPUB	OR	OFF	2006/03/21 10:15
L2	2	"10/673467" "10/673507"	US-PGPUB	OR	OFF	2006/03/21 10:15
L3	19	L1 and (rate).clm. US-20030078738-\$ or US-20040078319-\$ or US-20040102934-\$ or US-20050016947-\$).did. or (US-5719796-\$ or US-6571371-\$ or US-6615097-\$ or US-6628809-\$ or US-6643616-\$ or US-6728591-\$ or US-6757645-\$ or US-6763277-\$ or US-6774938-\$ or US-6802045-\$ or US-6812045-\$ or US-6905895-\$).did. or (US-5866437-\$ or WO-200177979-\$ or WO-200277589-\$ or US-20030135302-\$ or US-20040078319-\$ or US-20050010319-\$).did.	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15
L4	19	US-20030078738-\$ or US-20040078319-\$ or US-20040102934-\$ or US-20050016947-\$).did. or (US-5719796-\$ or US-6571371-\$ or US-6615097-\$ or US-6628809-\$ or US-6643616-\$ or US-6728591-\$ or US-6757645-\$ or US-6763277-\$ or US-6774938-\$ or US-6802045-\$ or US-6812045-\$ or US-6905895-\$).did. or (US-5866437-\$ or US-20030135302-\$ or US-20040078319-\$ or US-20050010319-\$).did.	US-PGPUB;	OR	OFF	2006/03/21 10:15
L5	8	L4 and rate	US-PGPUB;	OR	OFF	2006/03/21 10:15
L6	5	"10/673501" "10/673583" "10/673138" "10/673467" "10/673507"	US-PGPUB	OR	OFF	2006/03/21 10:15
L7	5	L6 and control\$6	US-PGPUB	OR	OFF	2006/03/21 10:15
L8	3	L6 and (control\$6).clm.	US-PGPUB	OR	OFF	2006/03/21 10:15
L9	2	L6 and (adjust\$6).clm.	US-PGPUB	OR	OFF	2006/03/21 10:15
L10	1	L6 and (nonlinear\$3 multivariate).clm.	US-PGPUB	OR	OFF	2006/03/21 10:15
L11	3	L3 and (nonlinear\$3 multivariate)	US-PGPUB	OR	OFF	2006/03/21 10:15
L12	1	L3 and (calibration)	US-PGPUB	OR	OFF	2006/03/21 10:15

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L13	9	L3 and (adjust)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/21 10:15
L14	3	L3 and (converg\$6)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/21 10:15
L15	4862	(ANSYS FLUENT CFRDC (Monte adj Carlo)) and simulat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/21 10:15
L16	253	(ANSYS) and simulat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/21 10:15
L17	3	(CFRDC) and simulat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/21 10:15
L18	674	(FLUENT) and simulat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/21 10:15

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L21	102	(ANSYS) with simulate\$4	US-PGPUB; USPAT; EPO; JPO; DERVENT; IBM_TDB; US-PGPUB; USPAT; EPO; JPO; DERVENT; IBM_TDB	OR	ON	2006/03/21 10:15
L22	138	(FLUENT) and simulate\$4 and (semiconductor wafer)	US-PGPUB; USPAT	OR	ON	2006/03/21 10:15
L23	5	"10/673501" "10/673138"	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15
L24	19	(US-20030078728-\$ or US-20040078319-\$ or US-20040102934-\$ or US-20050016947-\$).did. or (US-5719796-\$ or US-6571371-\$ or US-6615097-\$ or US-5628899-\$ or US-6643616-\$ or US-6728591-\$ or US-6757645-\$ or US-6763277-\$ or US-6774998-\$ or US-5802045-\$ or US-6812045-\$ or US-5903895-\$).did. or (US-5866437-\$ or US-20030135302-\$ or US-20040078319-\$ or US-20050010319-\$).did.	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15
L25	4	L24 and Geometric\$4	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15
L26	18542	(data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15
L27	7445	L26 and (semiconductor wafer)	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15
L28	1316	L26 and geometric	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15
L29	23	geometric with (data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15
L30	77	geometric and (data parameter) with (etch deposition coating lithography (thermal adj annealing)) with (semiconductor wafer)	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15
L31	2	(physical with geometric with parameters) with (data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15

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L32	5	(geometric with parameters) with (data parameter) with (etch deposition coating lithography (thermal adj annealing))	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15
L33	2	(input with size) with (etch deposition coating lithography (thermal adj annealing)) with (semiconductor wafer)	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15
L34	5	"10/673501" "10/673583" "10/673138"	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15
L35	50	("5886906" "5886363" "76031246" "6049661" "5095161" "4268951" "4782253" "5004774" "546742" "6030491" "6168891" "6178544" "6207630" "4343878" "4443532" "4481049" "4491530" "4500798" "4530587" "4564921" "4581706" "4582683" "4597985" "4602153" "4615782" "4769817" "4792893" "4801713" "4822716" "4842986" "4873561" "4905266" "4969748" "4984902" "4989166" "4999282" "5006717" "5017453" "5059516" "5198520" "5213996" "5243538" "5248956" "5288604" "5312722" "5312724" "5330884" "5331420" "5336752" "5339039").pn.	USPAT	OR	OFF	2006/03/21 10:15
L36	50	("5340697" "5340435" "54065309" "54069547" "5418397" "5427716" "54340697" "5438289" "5328223" "5455928" "5459020" "5474884" "5478702" "5498953" "54933501" "5495451" "5511005" "55237140" "5523022" "5558986" "5561612" "5571662" "5593608" "55966595" "5617322" "5619159" "5629877" "5637151" "5650947" "5654904" "5658706" "5663889" "5672468" "5677290" "5684723" "5694325" "5694052" "5699264" "5706200" "5709757" "5712794" "5714678" "5715170" "5730974" "5732724" "5745388).pn.	USPAT	OR	OFF	2006/03/21 10:15
L37	6	(US-20050016947-\$ or US-5629877-\$ or US-5377116-\$ or US-5719196-\$ or US-5802045-\$ or US-6812045-\$).did.	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15
L38	722	703/22.ccds.	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15
L39	5	"10/673501" "10/673583" "10/673138"	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15

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L40	5	"10/67350" "10/67358" "10/673138"	US-PGPUB	OR	OFF	2006/03/21 10:15	
L41	5	"10/673467" "10/673407"	US-PGPUB	OR	OFF	2006/03/21 10:15	
L42	0	semiconductor with tool with empirical with model	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15	
L43	0	(semiconductor with tool) and (empirical with model)	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15	
L44	0	(processing with tool) and (empirical with model)	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15	
L45	0	(semiconductor and tool) and (empirical with model)	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15	
L46	1	(tool) and (empirical with model)	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15	
L47	5	(empirical with model)	US-PGPUB; USPAT	OR	OFF	2006/03/21 10:15	